TEA1731LTS

GreenChip SMPS control IC

Rev. 2 — 16 August 2012 Product data sheet

1. General description

The TEA1731LTS is a low cost Switched Mode Power Supply (SMPS) controller IC intended for flyback topologies. The TEA1731LTS operates in peak current and frequency control mode. Frequency jitter has been implemented to reduce ElectroMagnetic Interference (EMI). Slope compensation is integrated for Continuous Conduction Mode (CCM) operation.

The TEA1731LTS IC features OverPower Protection (OPP). The controller accepts an overpower situation for a limited amount of time.

One pin is reserved for protection purposes. OverTemperature Protection (OTP) can be implemented with a minimal number of external components.

At low-power levels, the primary peak current is set to 25 % of the maximum peak current. The switching frequency is reduced to limit the switching losses. The combination of fixed frequency operation at high output power and frequency reduction at low output power provides high efficiency over the total load range.

The TEA1731LTS makes the design of low cost, highly efficient and reliable supplies for power requirements up to 75 W easier by requiring a minimum number of external components.

2. Features and benefits

- SMPS controller IC enabling low-cost applications
- Large input voltage range (12 V to 30 V)
- Integrated OverVoltage Protection (OVP) on VCC
- Very low supply current during start-up and restart (10 μA typical)
- Low supply current during normal operation (0.58 mA typical without load)
- Internal overpower time-out
- Overpower or high/low line compensation (NXP patent: 81421271EP01)
- Fixed switching frequency with frequency jitter to reduce EMI
- Frequency reduction at medium power operation to maintain high efficiency
- Frequency reduction with fixed minimum peak current to maintain high efficiency at low output power levels
- Frequency increase at peak power operation
- Slope compensation for CCM operation
- Adjustable soft start
- Low and adjustable OverCurrent Protection (OCP) trip level

- Protection input (for external OTP and external OVP)
- IC overtemperature protection

3. Applications

- All applications that require an efficient and cost-effective power supply solution up to 75 W.

4. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
TEA1731LTS	TSOP6	plastic surface-mounted package; 6 leads	SOT457

5. Block diagram

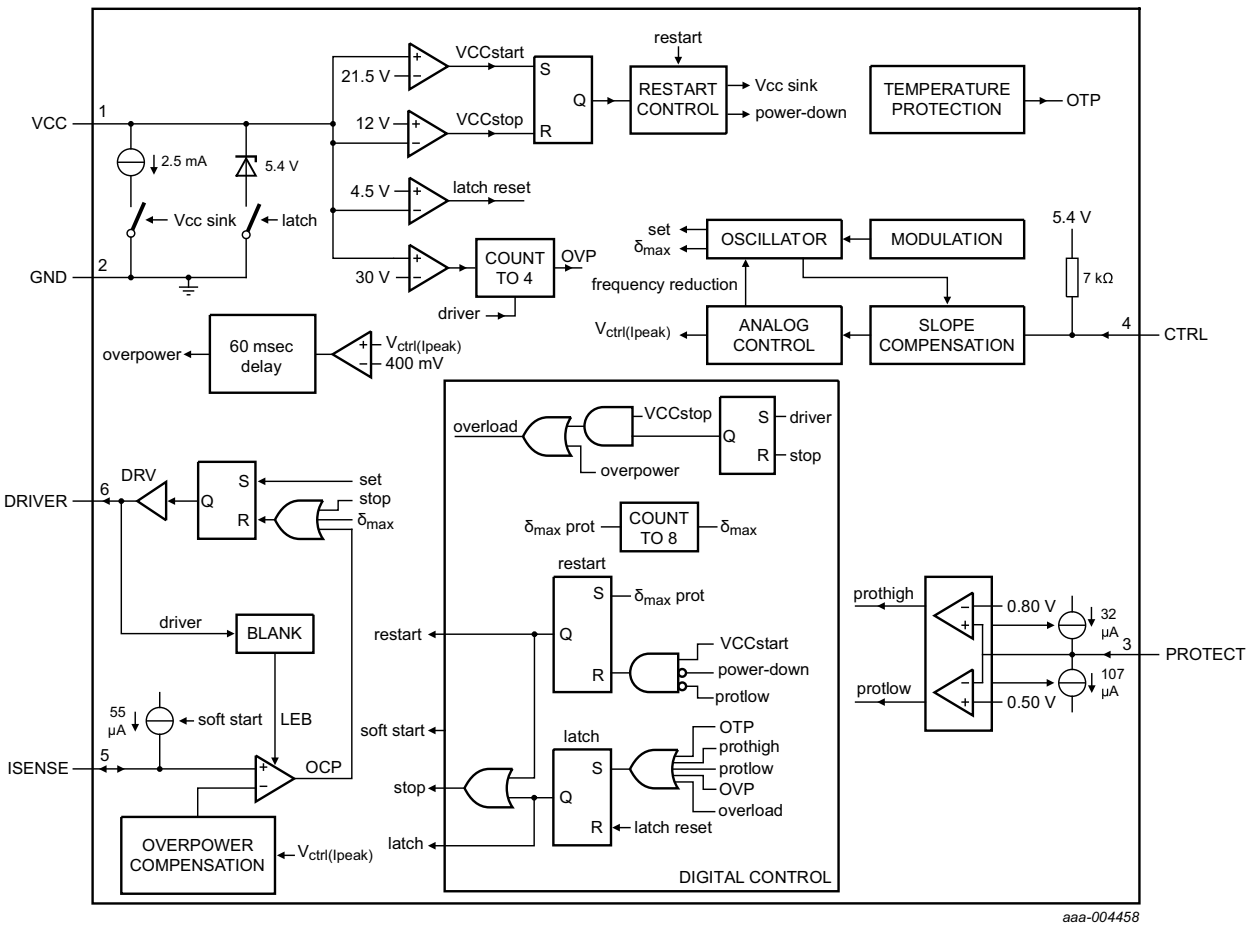


Fig 1. TEA1731LTS block diagram

6. Pinning information

6.1 Pinning

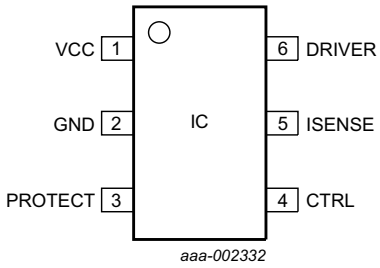


Fig 2. TEA1731LTS pin configuration

6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
VCC	1	supply voltage
GND	2	ground
PROTECT	3	general-purpose protection input
CTRL	4	control input
ISENSE	5	current sense input
DRIVER	6	gate driver output

7. Functional description

7.1 General control

The TEA1731LTS contains a controller for a flyback circuit. A typical configuration is shown in Figure 3.

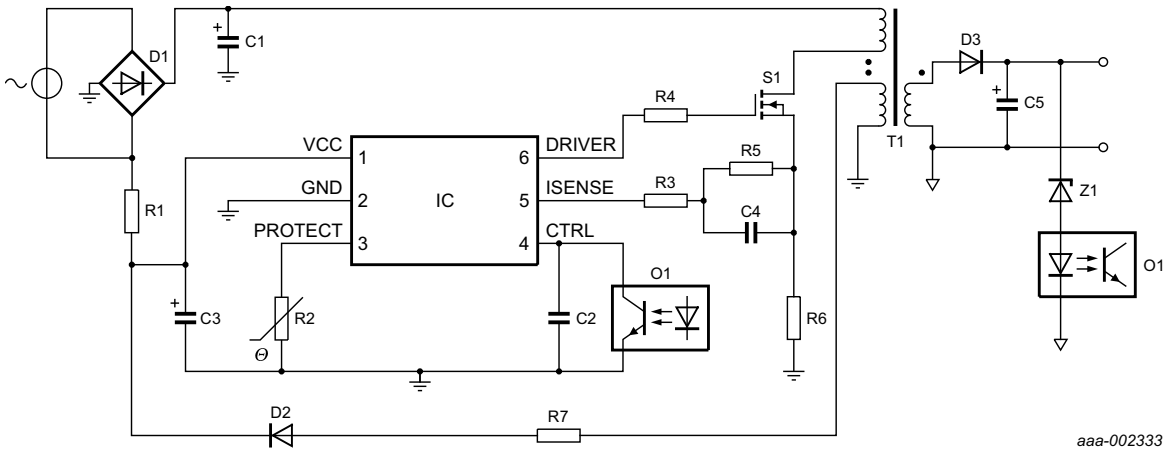


Fig 3. TEA1731LTS typical configuration

7.2 Start-up and UnderVoltage LockOut (UVLO)

Initially, the capacitor on the VCC pin, C3, is charged from the high-voltage mains via resistor R1.

As long as VCC is below $V_{startup}$, the IC current consumption is low (10 μA typical). When VCC reaches $V_{startup}$, the IC first waits for the PROTECT pin to reach the $V_{det(PROTECT)(L)}$ voltage. When $V_{det(PROTECT)(L)}$ is reached, the IC charges the ISENSE pin to the $V_{start(soft)}$ level and then starts switching. In a typical application, the auxiliary winding of the transformer takes over the supply voltage (see Figure 4).

If a protection is triggered, the controller stops switching. Depending on the protection triggered, it either causes a restart or latches the converter to an off-state.

A restart protection disables the switching of the IC. The supply voltage of the IC drops to the UVLO level. When the UVLO level is reached, the IC switches to Power-down mode, where it consumes a low supply current (10 μA typical). The switching recommences when the VCC capacitor is recharged to $V_{startup}$ via R1.

When a latched protection is triggered, the TEA1731LTS immediately enters Power-down mode. The VCC pin is clamped to a voltage just above the latch protection reset voltage ($V_{rst(latch)}$ + 0.9 V).

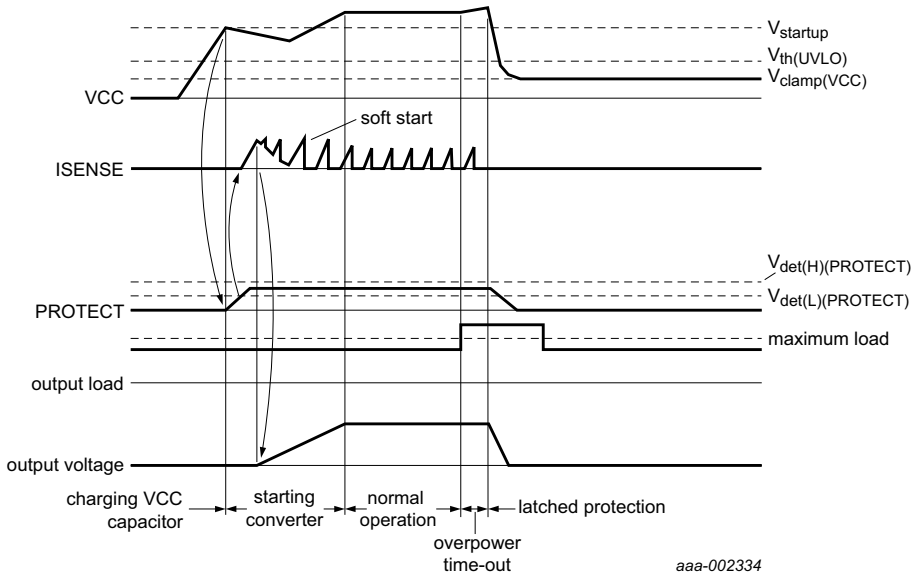


Fig 4. Start-up sequence, normal operation and latched protection

When the voltage on pin VCC drops below the $V_{th(UVLO)}$ level during normal operation, the controller stops switching. A VCC undervoltage, which does not occur during a start-up event, latches the IC in an off-state.

7.3 Supply management

All internal reference voltages are derived from a temperature compensated on-chip band gap circuit. Internal reference currents are derived from a trimmed and temperature compensated current reference circuit.

7.4 Overvoltage protection (pin VCC)

An OverVoltage Protection (OVP) circuit is connected to the VCC pin. When the V_{CC} exceeds $V_{th(OVP)}$ (30 V typical) for four consecutive switching cycles, the IC triggers the latched protection. When VCC drops below $V_{th(OVP)}$ before count = 4 is reached, the counter is reset to zero.

If a lower over voltage protection level is needed, a Zener diode can be connected between pins VCC and PROTECT.

7.5 Protection input (pin PROTECT)

Pin PROTECT is a general-purpose input pin, which can be used to switch off the converter (latched protection). The converter is stopped when the voltage on this pin is pulled above $V_{det(H)(PROTECT)}$ (0.8 V typical) or below $V_{det(L)(PROTECT)}$ (0.5 V typical) for four consecutive converter strokes. A current of 32 μA (typical) flows out of the chip when the pin voltage is $V_{det(L)(PROTECT)}$. A current of 107 μA (typical.) flows into the chip when the pin voltage is $V_{det(H)(PROTECT)}$.

The PROTECT input can be used for creating an (additional) overvoltage detection and an external OverTemperature Protection (OTP) function.

A small capacitor can be connected to the pin if the protections on this pin are not used.

An internal clamp of 4.1 V (typical) protects this pin from excessive voltages.

7.6 Duty cycle control (pin CTRL)

Pin CTRL regulates the output power of the converter. This pin is connected to an internal voltage source of 5.4 V via an internal resistor (typical resistance: 7 kΩ).

The CTRL pin voltage sets the peak current which is measured using the ISENSE pin (see Section 7.9). At low and medium output power the switching frequency is reduced (see Section 7.11). The maximum duty cycle is limited to 80 % (typical).

After eight consecutive converter strokes at maximum duty cycle the restart protection is activated. In a restart, the VCC capacitor is quickly discharged to the $V_{th(UVLO)}$ level and recharged to the start-up level from the high-voltage mains, before switching recommences. This occurs when the mains input voltage is removed.

7.7 Slope compensation (pin CTRL)

A slope compensation circuit is integrated for CCM. The slope compensation guarantees stable operation for duty cycles exceeding 50 %.

7.8 Overpower timer

A temporary overload situation is allowed. If $V_{ctrl(Ipeak)}$ (see Figure 1) set by pin CTRL exceeds 400 mV, an internal timer is started. If the overload situation continues to exist for more than 60 ms (typical), an OverPower Protection (OPP) is triggered (see Figure 5).

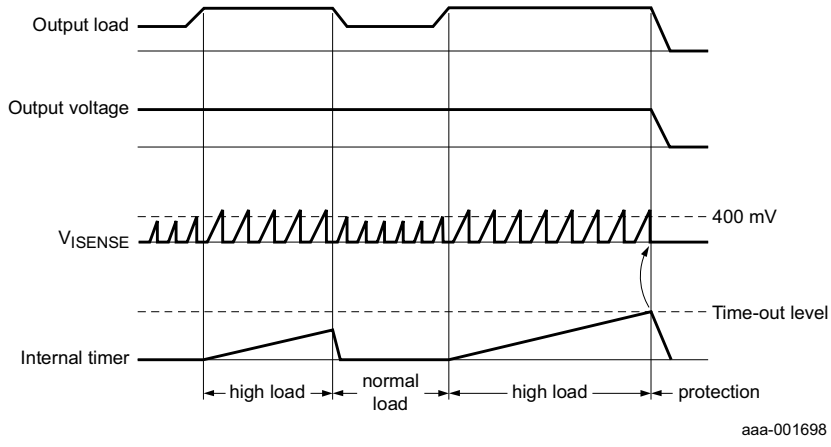


Fig 5. Overpower delay

The TEA1731LTS enters latched protection when overload time-out is reached.

7.9 Current mode control (pin ISENSE)

Current mode control is used because it ensures a good line regulation.

Pin ISENSE senses the primary current across an external resistor R6 and compares it with an internal control voltage. The internal control voltage is proportional to the CTRL pin voltage (see Figure 6).

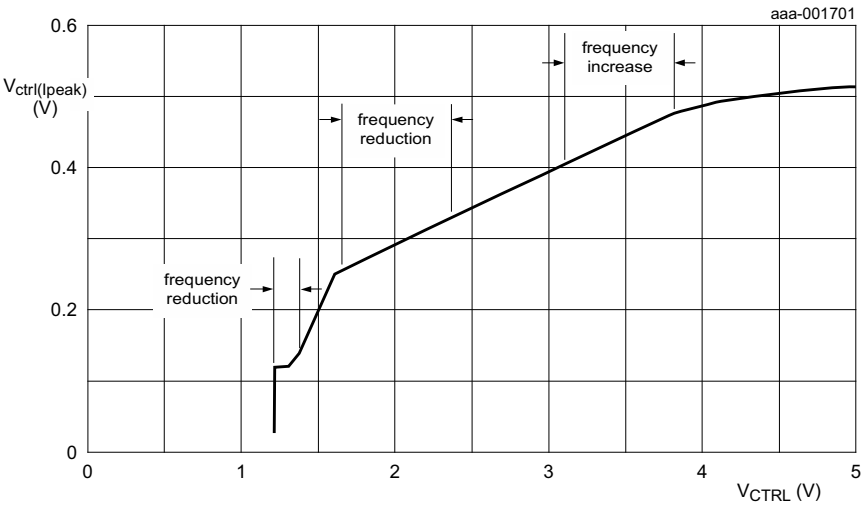


Fig 6. Peak current control

Leading edge blanking prevents false triggering due to capacitive discharge when switching on the external power switch (see Figure 7).

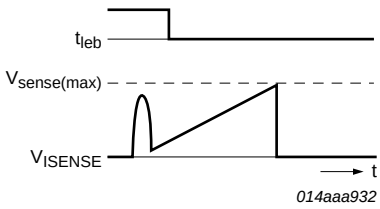


Fig 7. Leading edge blanking

7.10 Soft start-up (pin ISENSE)

A soft start is made to prevent audible noise during start-up or restart. Before the converter starts, soft start capacitor C4 on the ISENSE pin is charged. When the converter starts switching, the primary peak current slowly increases when the soft start capacitor discharges through the soft start resistor (R5, see Figure 3).

The soft start capacitor (C4) and resistor (R5) values chosen set the soft start time constant.

7.11 Peak power, high-power, medium power and low-power operation

During high-power operation, with the converter running at a 65 kHz (typical) fixed frequency, the power is controlled by varying the peak current. A peak-power mode is implemented to supply a short overload situation. In peak-power mode, both frequency and peak current are increased.

At reduced power levels, the converter enters the medium-power mode where the peak current is reduced. The switching losses are reduced by lowering the switching frequency to 27.5 kHz (typical).

When the power is further reduced to low power, a second frequency reduction is made. In low-power operation, the switching frequency of the converter is reduced while the peak current is set to 25 % of the maximum peak current (see Figure 6 and Figure 8).

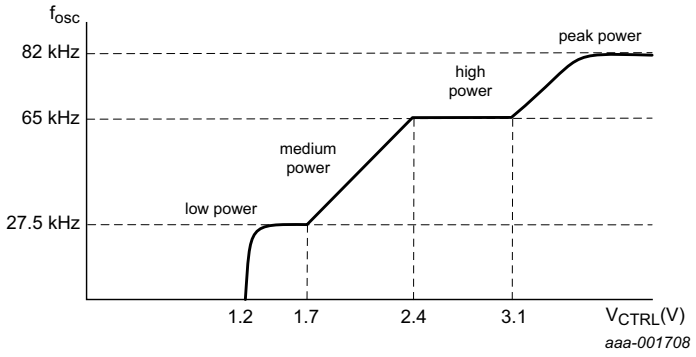


Fig 8. Frequency control

7.12 Overpower or high/low line compensation

Overpower compensation is built in to compensate for high/low line. The maximum continuous output power and the maximum peak power are about constant over the full mains input voltage range (see Figure 9). The rectified mains input voltage is measured by sensing the slope of the primary current from pin ISENSE. The slope information is then used to adjust the primary current by subtracting an offset $V_{(sense)offset}$ from the internal control voltage $V_{ctrl(Ipeak)}$ cycle-by-cycle (NXP patent: 81421271EP01).

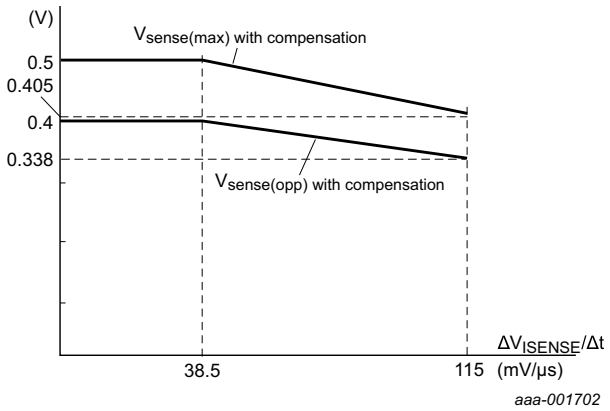


Fig 9. Overpower compensation

7.13 Driver (pin DRIVER)

The driver circuit to the gate of the power MOSFET has a current sourcing capability of typically 300 mA and a current sink capability of typically 750 mA. This enables a fast turn-on and turn-off of the power MOSFET for efficient operation.

7.14 OverTemperature Protection (OTP)

Integrated overtemperature protection ensures that the IC stops switching if the junction temperature exceeds the thermal shutdown limit.

OTP is a latched protection. It can be reset by removing the voltage on pin VCC.

8. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Voltages					
V_{CC}	supply voltage	continuous	–0.4	+30	V
		t < 100 ms	-	35	V
$V_{PROTECT}$	voltage on pin PROTECT	current limited	–0.4	+5	V
V_{CTRL}	voltage on pin CTRL		–0.4	+5.5	V
V_{ISENSE}	voltage on pin ISENSE	current limited	–0.4	+5	V
Currents					
I_{VCC}	current on pin VCC	δ < 10 %	-	0.4	A
$I_{I(PROTECT)}$	input current on pin PROTECT		–1	+1	mA
I_{CTRL}	current on pin CTRL		–3	0	mA
I_{ISENSE}	current on pin ISENSE		–10	+1	mA
I_{DRIVER}	current on pin DRIVER	δ < 10 %	–0.4	+1	A
General					
P_{tot}	total power dissipation	T_{amb} < 75 °C	-	0.29	W
T_{stg}	storage temperature		–55	+150	°C
T_j	junction temperature		–40	+150	°C
ESD					
V_{ESD}	electrostatic discharge voltage	class 1			
		human body model [1]	-	4000	V
		changed device model	-	750	V

[1] Equivalent to discharging a 100 pF capacitor through a 1.5 kΩ series resistor.

9. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air; single layer JEDEC test board	259	K/W
$R_{th(j-c)}$	thermal resistance from junction to case	in free air; JEDEC test board	152	K/W

10. Characteristics

Table 5. Characteristics

T_{amb} = 25 °C; V_{CC} = 20 V; all voltages are measured with respect to ground (pin 2); currents are positive when flowing into the IC; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Supply voltage management (pin VCC)						
$V_{startup}$	start-up voltage		19.3	21.5	23.8	V
$V_{th(UVLO)}$	undervoltage lockout threshold voltage		11.2	12.5	13.8	V
$V_{th(ovp)}$	overvoltage protection threshold voltage		29	30	31	V
$N_{cy(ovp)}$	number of overvoltage protection cycles		-	4	-	
$V_{clamp(VCC)}$	clamp voltage on pin VCC	activated during latched protection; I_{CC} = 100 µA	-	$V_{rst(latch)}$ + 0.9	-	V
		activated during latched protection, I_{CC} = 1 mA	-	-	$V_{rst(latch)}$ + 3.5	V
$I_{CC(restart)}$	restart supply current		1	2.5	-	mA
V_{hys}	hysteresis voltage	$V_{startup}$ - $V_{th(UVLO)}$	6.6	9.1	11.6	V
$I_{CC(startup)}$	start-up supply current	V_{CC} < $V_{startup}$	5	10	15	µA
$I_{CC(oper)}$	operating supply current	no-load on pin DRIVER; δ = 2 %; excluding optocurrent	-	0.58	-	mA
		no-load on pin DRIVER; δ = 25 %, excluding optocurrent	-	0.62	-	mA
$V_{rst(latch)}$	latched reset voltage		3.5	4.5	5.5	V
Protection input (pin PROTECT)						
$V_{det(L)(PROTECT)}$	LOW-level detection voltage on pin PROTECT		0.47	0.50	0.53	V
$V_{det(H)(PROTECT)}$	HIGH-level detection voltage on pin PROTECT		0.75	0.8	0.85	V
$I_{O(PROTECT)}$	output current on pin PROTECT	$V_{PROTECT}$ = $V_{low(PROTECT)}$	−34	−32	−30	µA
		$V_{PROTECT}$ = $V_{high(PROTECT)}$	87	107	127	µA
$V_{clamp(PROTECT)}$	clamp voltage on pin PROTECT	$I_{I(PROTECT)}$ = 200 µA [1]	3.5	4.1	4.7	V
Peak current control (pin CTRL)						
V_{CTRL}	voltage on pin CTRL	for minimum flyback peak current	1	1.3	1.6	V
$R_{int(CTRL)}$	internal resistance on pin CTRL		5	7	9	kΩ
$I_{O(CTRL)}$	output current on pin CTRL	V_{CTRL} = 1.4 V	−0.7	−0.5	−0.3	mA

Table 5. Characteristics *...continued*

T_{amb} = 25 °C; V_{CC} = 20 V; all voltages are measured with respect to ground (pin 2); currents are positive when flowing into the IC; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Pulse width modulator						
f_{osc}	oscillator frequency	peak power	75	82	89	kHz
		high power	60.5	65	69.5	kHz
		medium power	24	27.5	31	kHz
f_{mod}	modulation frequency		210	280	350	Hz
Δf_{mod}	modulation frequency variation	high power	±3	±4	±5	kHz
δ_{max}	maximum duty cycle		-	80	-	%
$N_{cy(dmax)}$	number of switching cycles with maximum duty cycle		-	8	-	
$V_{start(red)f}$	frequency reduction start voltage	pin CTRL dropping to low power	1.1	1.4	1.7	V
$V_{\delta(zero)}$	zero duty cycle voltage	pin CTRL	0.9	1.2	1.5	V
Overpower protection						
$t_{to(opp)}$	overpower protection time-out time		-	60	-	ms
Current sense and overpower compensation (pin ISENSE)						
$V_{sense(max)}$	maximum sense voltage	$\Delta V/\Delta t$ = 0 V/s	0.47	0.50	0.53	V
$t_{PD(sense)}$	sense propagation delay		-	146	-	ns
$V_{th(sense)opp}$	overpower protection sense threshold voltage		370	400	430	mV
$V_{offset(opc)}$	overpower compensation offset voltage	V_{sense} = 400 mV; $\Delta V/\Delta t$ = 115 mV/µs	38	62	86	mV
		V_{sense} = 500 mV; $\Delta V/\Delta t$ = 115 mV/µs	60	95	130	mV
$\Delta V_{ISENSE}/\Delta t$	slope compensation voltage on pin ISENSE	high-power mode	-	20	-	mV/µs
t_{leb}	leading edge blanking time		275	325	375	ns
Soft start (pin ISENSE)						
$I_{start(soft)}$	soft start current		–63	–55	–47	µA
$V_{start(soft)}$	soft start voltage	V_{CTRL} = 4 V; enable voltage	-	$V_{sense(max)}$	-	V
$R_{start(soft)}$	soft start resistance		12	-	-	kΩ
Driver (pin DRIVER)						
$I_{source(DRIVER)}$	source current on pin DRIVER	V_{DRIVER} = 2 V	-	–0.3	–0.25	A

Table 5. Characteristics *...continued*

T_{amb} = 25 °C; V_{CC} = 20 V; all voltages are measured with respect to ground (pin 2); currents are positive when flowing into the IC; unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{sink(DRIVER)}$	sink current on pin DRIVER	V_{DRIVER} = 2 V	0.25	0.3	-	A
		V_{DRIVER} = 10 V	0.6	0.75	-	A
$V_{O(DRIVER)max}$	maximum output voltage on pin DRIVER		9	10.5	12	V
Temperature protection						
$T_{pl(IC)}$	IC protection level temperature		130	140	150	°C

[1] The clamp voltage on the PROTECT pin is lowered when the IC is in Power-down mode. (latched or restart protection)

11. Application information

A power supply with the TEA1731LTS is a flyback converter operating in continuous conduction mode. See Figure 10.

Capacitor C3 buffers the IC supply voltage, which is powered via resistor R1 for start-up and via the auxiliary winding during normal operation. Sense resistor R6 converts the current through MOSFET S1 into a voltage on pin ISENSE. The value of resistor R6 defines the maximum primary peak current through MOSFET S1. Resistor R7 reduces the peak current to capacitor C3.

Resistor R5 and capacitor C4 define the soft start time. Resistor R3 is added to prevent that soft start capacitor C4 from is charged during normal operation due to negative voltage spikes across current sense resistor R6.

Capacitor C2 is added to reduce noise on the CTRL pin.

Resistor R4 is required to limit the current spikes to pin DRIVER because of parasitic inductance of current sense resistor R6. Resistor R4 also dampens possible oscillations of MOSFET S1. Adding a bead on the gate pin of MOSFET S1 can be required to prevent local oscillations of the MOSFET.

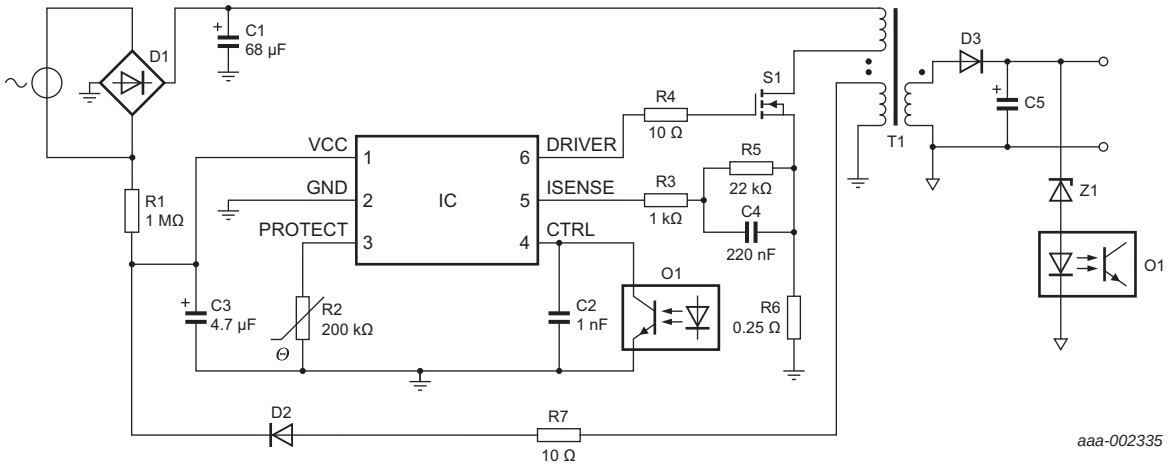
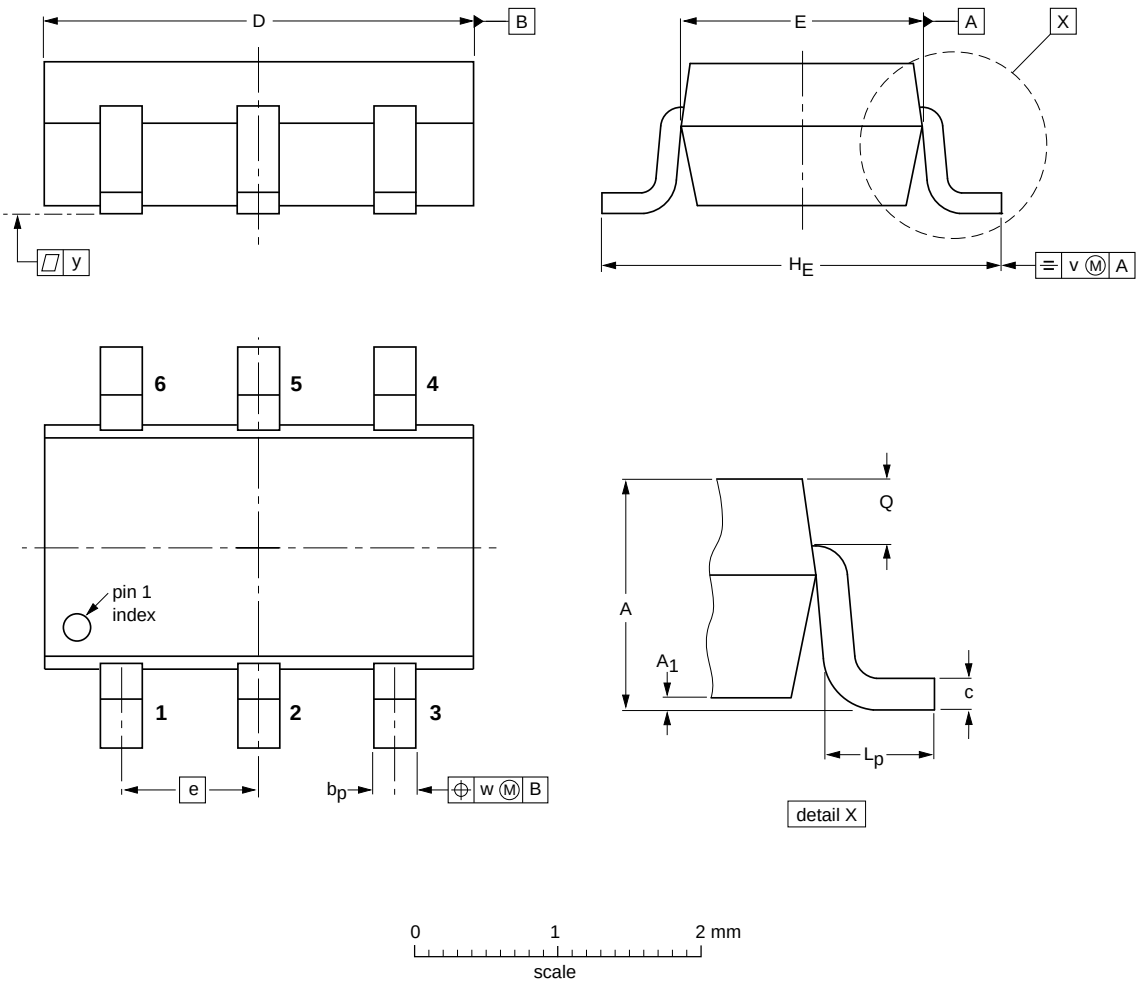


Fig 10. TEA1731LTS application diagram

12. Package outline

Plastic surface-mounted package (TSOP6); 6 leads **SOT457**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b_p	c	D	E	e	H_E	L_p	Q	v	w	y
mm	1.1 0.9	0.1 0.013	0.40 0.25	0.26 0.10	3.1 2.7	1.7 1.3	0.95	3.0 2.5	0.6 0.2	0.33 0.23	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT457			SC-74			~~05-11-07~~ 06-03-16

Fig 11. SOT457 (TSOP6)

13. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
TEA1731LTS v.2.1	20120816	Product data sheet	-	TEA1731LTS v.2
Modifications:	• R4 value changed in Figure 10 “TEA1731LTS application diagram”.			
TEA1731LTS v.2	20120731	Product data sheet	-	TEA1731LTS v.1
TEA1731LTS v.1	20120206	Objective data sheet	-	-

14. Legal information

14.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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15. Contact information

For more information, please visit: **http://www.nxp.com**

For sales office addresses, please send an email to: **salesaddresses@nxp.com**

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